



Material Content Data Sheet



| Sales Product Name | | BC 860CW H6327 | | Issued | | 29. August 2013 | | |
|---------------------------|--------------------|----------------|--------------------|----------------|------------------|-----------------|--------------------|-----------|
| MA# | | MA000845008 | | | | | | |
| Package | | PG-SOT323-3-1 | | Weight* | | 5.98 mg | | |
| Construction Element | Material Group | Substances | CAS# if applicable | Weight [mg] | Average Mass [%] | Sum [%] | Average Mass [ppm] | Sum [ppm] |
| chip | non noble metal | arsenic | 7440-38-2 | 0.000 | 0.00 | | 39 | |
| | noble metal | gold | 7440-57-5 | 0.023 | 0.38 | | 3830 | |
| | inorganic material | silicon | 7440-21-3 | 0.078 | 1.31 | 1.69 | 13085 | 16954 |
| leadframe | inorganic material | silicon | 7440-21-3 | 0.001 | 0.01 | | 88 | |
| | non noble metal | titanium | 7440-32-6 | 0.003 | 0.04 | | 439 | |
| | non noble metal | chromium | 7440-47-3 | 0.008 | 0.13 | | 1318 | |
| | non noble metal | copper | 7440-50-8 | 2.617 | 43.75 | 43.93 | 437395 | 439240 |
| wire | non noble metal | copper | 7440-50-8 | 0.005 | 0.08 | 0.08 | 847 | 847 |
| encapsulation | organic material | carbon black | 1333-86-4 | 0.031 | 0.52 | | 5191 | |
| | plastics | epoxy resin | - | 0.668 | 11.16 | | 111608 | |
| | inorganic material | silicondioxide | 60676-86-0 | 2.407 | 40.23 | 51.91 | 402308 | 519107 |
| leadfinish | non noble metal | tin | 7440-31-5 | 0.133 | 2.22 | 2.22 | 22179 | 22179 |
| plating | noble metal | silver | 7440-22-4 | 0.010 | 0.17 | 0.17 | 1673 | 1673 |
| *deviation | < 10% | | Sum in total: | | | 100.00 | | 1000000 |

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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